

LTM9003 108LD 15.00mm X 11.25mm X 2.32mm (TABLE OF MATERIAL DECLARATION)

The LTM9003 is RoHS compliant per EU RoHS Directive 2003/95/EC.

It contains less than 100ppm cadmium (Cd) and less than 1,000ppm of each - lead (Pb), mercury (Hg), hexavalent chromium (Cr+), polybrominated biphenyl (PBB) and polybrominated diphenyl ether (PBDE)

No.	Part Name	Material Name	Component Weight (gram)	Materials Analysis (element)	CAS Number	Material Mass (gram)	Materials Analysis (weight %)
1	Substrate	Circuit Board	0.1992	Barium Compounds	7727-43-7	0.00299	1.50000
				Filler Substances (Silica Crystalline)	-	0.07951	39.91457
				Copper Metal	7440-50-8	0.11155	56.00000
				Copper Compounds	1328-53-6	0.00004	0.01800
				Ecotoxic substances	7439-92-1	0.00000	0.00043
				Gold metal or alloy	7440-57-5	0.00092	0.46000
				Nickel	7440-02-0	0.00418	2.10000
				Zinc	7440-66-6	0.00001	0.00700
2	Solder Paste	Alloy	0.0103	Sn	7440-31-5	0.00980	95.00000
				Sb	7440-36-0	0.00052	5.00000
3	Die attach adhesive	Epoxy Resin	0.0034	epoxy	—	0.00340	100.00000
4	Passive/Active Components		0.0648	Capacitor	-	0.05719	88.23511
				Resistor	-	0.00181	2.78618
				Inductor	-	0.00582	8.97717
				Diode	-	0.00000	0.00000
5	Active lcs	Silicon	0.0038	Silicon	7440-21-3	0.00380	100.00000
6	Wire	Gold	0.0017	Au	7440-57-5	0.00171	99.99000
7	LT5557EUF	see LTC web site for	0.0370	see LTC web site	—	0.03700	100.00000
8	Encapsulation	Epoxy Resin	0.6276	Fused Silica	60676-86-0	0.48451	77.20000
				Epoxy Resin	-	0.05586	8.90000
				Phenol Resin	-	0.05586	8.90000
				Crytalline Silica	14808-60-7	0.01883	3.00000
				Carbon Black	1333-86-4	0.00314	0.50000
				Metal Hydroxide	-	0.00941	1.50000
Total Package Weight			0.9479				

Note: Composition derived from MSDS and material C of C from Vendors
 Component Weight based on assembly of generic parts